- Q Devices Meet Automotive Performance Requirements
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- EPIC[™] (Enhanced-Performance Implanted CMOS) Process
- Operating Range 2-V to 5.5-V V_{CC}
- Latch-Up Performance Exceeds 250 mA Per JESD 17

description

The SN74AHC04Q contains six independent inverters. This device performs the Boolean function $Y = \overline{A}$.

ORDERING INFORMATION

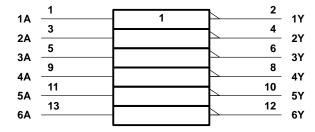
TA	PACKA	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC - D	Tape and reel	SN74AHC04QDR	AHC04Q
	TSSOP – PW	Tape and reel	SN74AHC04QPWR	HA04Q

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic symbol‡



[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram, each inverter (positive logic)





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TEXAS INSTRUMENTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Output voltage range, V _O (see Note 1)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	86°C/W
PW package	113°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
VCC	Supply voltage		2	5.5	V
	V _{CC} = 2 V		1.5		
V_{IH}	High-level input voltage	V _{CC} = 3 V	2.1		V
		$V_{CC} = 5.5 V$	3.85		
		V _{CC} = 2 V		0.5	
V_{IL}	Low-level input voltage			0.9	V
				1.65	
٧ _I	Input voltage		0	5.5	V
٧o	Output voltage		0	VCC	V
		V _{CC} = 2 V		-50	μΑ
lOH	High-level output current	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		-4	mA
		$V_{CC} = 5 V \pm 0.5 V$		-8	IIIA
		V _{CC} = 2 V		50	μΑ
IOL	Low-level output current $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$			4	A
		V _{CC} = 5 V ± 0.5 V		8	mA
A+/A>-	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		100	ns/V
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 5 V \pm 0.5 V$		20	115/ V
TA	Operating free-air temperature		-40	125	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V	T,	ղ = 25°C	;	MIN	MAV	UNIT
PARAMETER	TEST CONDITIONS	VCC	MIN TYP MAX		MAX			
		2 V	1.9	2		1.9		
	I _{OH} = -50 μA	3 V	2.9	3		2.9		
V _{OH}		4.5 V	4.4	4.5		4.4		V
	$I_{OH} = -4 \text{ mA}$	3 V	2.58			2.48		
	I _{OH} = -8 mA	4.5 V	3.94			3.8		
		2 V			0.1		0.1	
	I _{OL} = 50 μA	3 V			0.1		0.1	
V _{OL}		4.5 V			0.1		0.1	V
	I _{OL} = 4 mA	3 V			0.36		0.5	
	I _{OL} = 8 mA	4.5 V			0.36		0.5	
lį	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1		±1	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			2		20	μΑ
Ci	$V_I = V_{CC}$ or GND	5 V		2	10			pF

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T _A = 25°C			MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIN	WAX	UNIT
^t PLH	۸	Y	C _L = 15 pF		5	8.9	1	10.5	ne
^t PHL	А				5	8.9	1	10.5	ns
^t PLH	۸	Y	C _L = 50 pF		7.5	11.4	1	13	no
^t PHL	Α				7.5	11.4	1	13	ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T _A = 25°C			MIN	MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	IVIIIV	WAX	CIVIT
^t PLH		V	C _L = 15 pF		3.8	5.5	1	6.5	20
^t PHL	А	Ĭ			3.8	5.5	1	6.5	ns
^t PLH	Λ.	V	C _L = 50 pF		5.3	7.5	1	8.5	ne
^t PHL	A	T			5.3	7.5	1	8.5	ns

noise characteristics, $V_{CC} = 5 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 4)

	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.4		V
V _{OL(V)}	Quiet output, minimum dynamic VOL		-0.4		V
VOH(V)	Quiet output, minimum dynamic VOH		4.8		V
V _{IH} (D)	High-level dynamic input voltage	3.5			V
V _{IL(D)}	Low-level dynamic input voltage			1.5	V

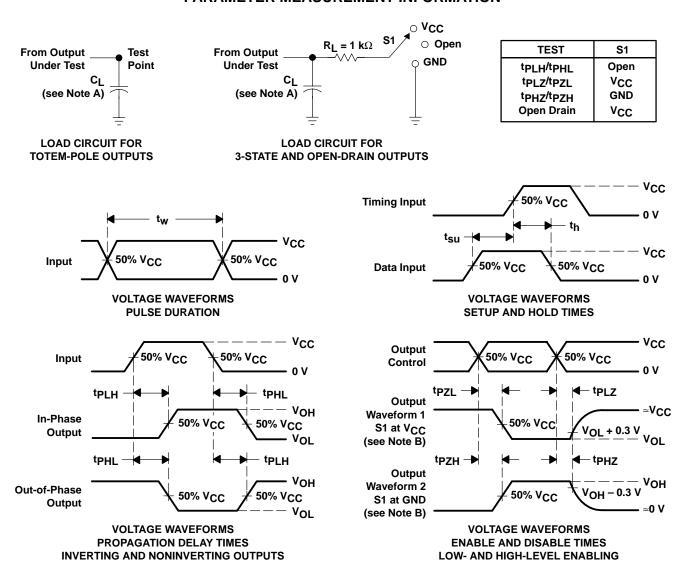
NOTE 4: Characteristics are for surface-mount packages only.



operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST C	ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	12	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f \leq 3$ ns. $t_f \leq 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
SN74AHC04QDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHC04Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



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